

CIRCUIT BOARD PROCESSING TECHNIQUES  
USING SOLDER FUSING

ABSTRACT OF THE DISCLOSURE

5           A circuit board processing system has a circuit board fabrication stage  
configured to fabricate a circuit board having a set of circuit board pads, and a solder  
fusing stage coupled to the circuit board fabrication stage. The solder fusing stage is  
configured to (i) apply flux and solder concurrently to the set of circuit board pads, and  
(ii) activate the flux and melt the solder to form a set of substantially flat solder coatings  
10 which is fused to the set of circuit board pads. The circuit board processing system  
further includes a washing stage coupled to the solder fusing stage. The washing stage  
is configured to remove contamination from a surface of the circuit board having the  
circuit board pads and from the set of substantially flat solder coatings which is fused to  
the set of circuit board pads. Such a system is well-suited for lead-free solder.

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